



## Description

TPSeal® PP 15C1 is a metallocene random copolymer Polypropylene (mPP) Compound.

TPSeal® PP 15C1 is intended for the manufacture of rotomoulded items and available in natural, in pellets or in powder.

It is also available under a black colour.

## Main Characteristics

Its specific molecular structure ensures:

- ✓ Low warpage, low shrinkage
- ✓ High gloss
- ✓ Improved impact properties

## Application

Structural parts, design (furniture), house appliances, ...

## Properties

Property	Method	Unit	Typical value (*)
Melt Flow Rate (230°C-2.16kg)	ISO 1133/D	g/10min	<b>15.0</b>
Melting Temperature	ISO 11357	°C	<b>140</b>
Vicat Softening Point (Method A50)	ISO 306	°C	<b>114</b>
Heat Deflection Temperature (Method B)	ISO 75	°C	<b>64</b>
Tensile modulus	ISO 527	MPa	<b>800</b>
Tensile strength @yield	ISO 527	MPa	<b>20</b>
Flexural modulus	ISO 178	MPa	<b>850</b>

(\*) Data not intended for specification purposes

## Processing conditions

It is recommended to keep product dry prior use for production.

## Handling and storage

Please refer to the material safety data sheet (MSDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the MSDS of our product.

MSDS may be obtained from the website: [www.polymers.totalenergies.com](http://www.polymers.totalenergies.com)

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